

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

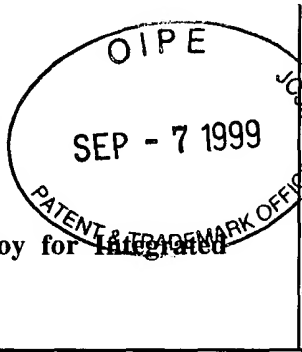
In Re the Application of:

DONALD S. GARDNER, ET AL.

Application No.: 09/253,306

Filed: February 19, 1999

For: **Interconnection Alloy for Integrated Circuits**



Art Group: 1775

Examiner:

RECEIVED
SEP - 9 1999
TTC 1100 MAIL ROOM

#1 1/2
10/28/99
Lumber

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Pursuant to Rule 1.97, Applicant desires to make of record the references set forth on the attached Form PTO 1449. Copies of these references are submitted herewith.

It is hereby stated that this Information Disclosure Statement is being filed prior to the issuance of the initial office Action, therefore no petition or fee is required. However, in the event a petition is needed for consideration of this Information Disclosure Statement, Applicant hereby so petitions. Please charge any additional fee due to Deposit Account 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Date: 9/1/99

William T. Babbitt

William Thomas Babbitt, Reg. No. 39,591

12400 Wilshire Blvd., 7th Floor
Los Angeles, California 90025
Telephone: (310) 207-3800

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 to the Patent and Trademark Office on: September 1, 1999

Nedy Calderon
Nedy Calderon

9/1/99

Date

RECEIVED
SEP 15 1999
TTC 2000 MAIL ROOM